

Intel® Desktop Board DG43GT

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Specifications

- Essentials

Status	End of Interactive Support
Launch Date	Q3'09
Board Form Factor	microATX
Socket	LGA775
Recommended Customer Price	N/A
Datasheet	Link
Board Chipset	Intel® G43 Express Chipset (Intel® 82G43 Graphics and Memory Controller Hub)

- Memory Specifications

Max Memory Size (dependent on memory type)	8 GB
Memory Types	DDR2 667/800
Max # of Memory Channels	2
Max # of DIMMs	4
ECC Memory Supported †	No

- Graphics Specifications

Integrated Graphics †	Yes
Graphics Output	HDMI, DVI-I
# of Displays Supported †	2
Discrete Graphics	PCIe x16

- Expansion Options

PCI Support	1
PCIe x1 Gen 2.x	2
PCIe x4 Gen 2.x	0
PCIe x8 Gen 2.x	0
PCIe x16 Gen 2.x	1

- I/O Specifications

USB 2.0 Configuration (Back + Internal)	6+6
Total # of SATA Ports	4
# of eSATA Ports	0
RAID Configuration	N/A
# of PATA Ports	1
# of Parallel Ports	1
# of Serial Ports	1
Audio (back channel + front channel)	8-ch
Integrated LAN	10/100/1000
Firewire	1+1

- Package Specifications

Max CPU Configuration	1
Low Halogen Options Available	See MDDDS

- Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) †	No
Intel® vPro Technology †	No
Intel® ME Firmware Version	N/A
Intel® Remote Wake Technology	Yes
Intel® Remote PC Assist Technology	No
Intel® CIRA Technology	No
TPM	No
Intel® Quiet System Technology	Yes
Intel® HD Audio Technology	Yes
Intel® Matrix Storage Technology	No

- Intel® Platform Protection Technology

Trusted Execution Technology †	No
Anti-Theft Technology	No

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Refer to Datasheet for formal definitions of product properties and features.

Announced SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

† This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components on the finished assembly meet J5-709 requirements, and the PCB substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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